

Amendments to the Claims

Please cancel claims 19 and 32-36 without prejudice.

The following listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

- 1-13. (cancelled)
14. (currently amended): A method of coupling a carbon foam material to an integrated circuit comprising:

coating a carbon foam material with a first solder; and
coating a surface of an integrated circuit with a second solder; and
coupling the carbon foam material coated with the first solder to the integrated circuit coated with the second solder such that thermal energy from the integrated circuit is transferred to the carbon foam material.
15. (previously presented): The method of claim 14, further comprising cleaning a surface of the integrated circuit.
16. (previously presented): The method of claim 14, further comprising cleaning a surface of the integrated circuit by backspattering the surface of the integrated circuit with an inert gas.
17. (previously presented): The method of claim 14, further comprising cleaning a surface of the carbon foam material.

18. (previously presented): The method of claim 14, further comprising cleaning a surface of the carbon foam material by backspattering with an inert gas.

Claims 19-21 (cancelled)

22. (currently amended): The method of claim 14, wherein a the second solder couples the integrated circuit and the carbon foam material, and wherein the second solder comprises copper, nickel, gold, silver, lead, silicon, indium, bismuth, titanium, tin, or mixtures thereof.
23. (previously presented): The method of claim 14, wherein coupling the carbon foam material to the integrated circuit comprises coupling the integrated circuit and the carbon foam material with a universal solder.
24. (previously presented): The method of claim 14, wherein coupling the carbon foam material to the integrated circuit comprises coupling the integrated circuit and the carbon foam material with adhesives.
25. (previously presented): The method of claim 14, further comprising forming a silicide on a surface of the integrated circuit.
26. (previously presented): The method of claim 25, further comprising coating a surface of the silicide with an adherent metal.
27. (previously presented): The method of claim 14, wherein coupling the carbon foam material to the integrated circuit comprises heating the carbon foam material with the integrated circuit in an inert atmosphere furnace.

28. (previously presented): The method of claim 14, wherein coupling the carbon foam material to the integrated circuit comprises heating the carbon foam material with the integrated circuit in a reducing atmosphere furnace.
29. (previously presented): The method of claim 14, wherein coupling the carbon foam material to the integrated circuit comprises heating the carbon foam material with the integrated circuit in a vacuum furnace.
30. (previously presented): The method of claim 14, wherein coupling the carbon foam material to the integrated circuit comprises heating the carbon foam material with the integrated circuit on a hot plate.

Claim 31-36 (cancelled)